# **TEA1623P; TEA1623PH**

### **STARplug**<sup>TM</sup>

Rev. 01 — 17 March 2004

**Product data sheet** 

### 1. General description

The TEA1623P; TEA1623PH is a Switched Mode Power Supply (SMPS) controller IC that operates directly from the rectified universal mains. It is implemented in the high voltage EZ-HV™ SOI process, combined with a low voltage BICMOS process.

The device includes a high voltage power switch and a circuit for start-up directly from the rectified mains voltage. A dedicated circuit for valley switching is built in, which makes a very efficient slim-line electronic power-plug concept possible.

In its most basic version of application, the TEA1623P; TEA1623PH acts as a voltage source. Here, no additional secondary electronics are required. A combined voltage and current source can be realized with minimum costs for external components. Implementation of the TEA1623P; TEA1623PH renders an efficient and low cost power supply system.

### 2. Features

- Designed for general purpose supplies
- Integrated power switch: 6.5 Ω and 650 V
- Operates from universal AC mains supplies: 80 V to 276 V
- Adjustable frequency for flexible design
- RC oscillator for load insensitive regulation loop constant
- Valley switching for minimum switch-on loss
- Frequency reduction at low power output for low standby power: <100 mW</p>
- Adjustable overcurrent protection
- Undervoltage protection
- Temperature protection
- Short winding protection
- Safe restart mode for system fault conditions
- Simple application with both primary and secondary (opto) feedback
- Available in 8-pin and 16-pin DIP package.

## 3. Applications

- Adapters
- Set-Top Box (STB)
- DVD

- VCD
- CD(R)
- PC Silverbox standby SMPS.





### 4. Quick reference data

Table 1: Quick reference data

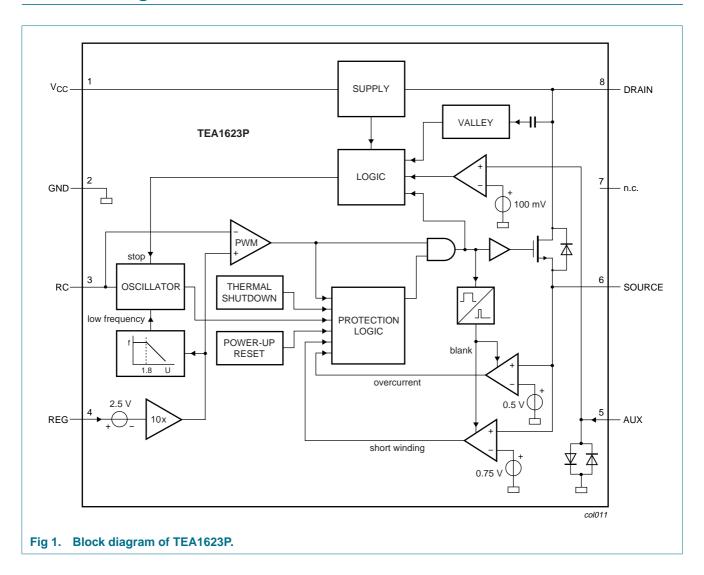
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V <sub>CC(max)</sub>	maximum supply voltage		-	-	40	V
$V_{DRAIN(max)}$	maximum voltage at pin DRAIN	T <sub>j</sub> > 0 °C	-	-	650	V
I <sub>DRAIN</sub>	supply current drawn from pin DRAIN	no auxiliary supply	-	0.5	-	mA
R <sub>DSon</sub>	drain-source on-state	$I_{SOURCE} = -0.5 A$				
	resistance	T <sub>j</sub> = 25 °C	-	6.5	7.5	Ω
		T <sub>j</sub> = 100 °C	-	9.0	10.0	Ω
f <sub>osc</sub>	oscillator frequency range		10	-	200	kHz
T <sub>amb</sub>	ambient temperature		-20	-	+85	°C

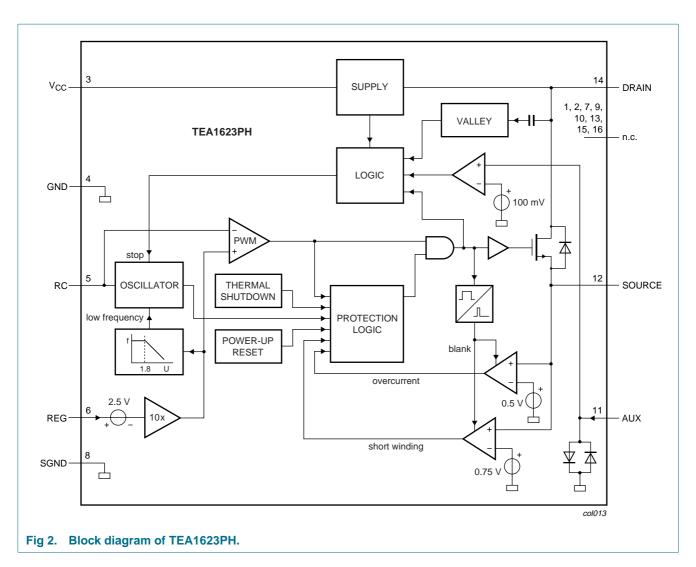
## 5. Ordering information

**Table 2: Ordering information** 

Type number	Package							
	Name	Description	Version					
TEA1623P	DIP8	plastic dual in-line package; 8 leads (300 mil)	SOT97-1					
TEA1623PH	DIP16	plastic dual in-line package; 16 leads (300 mil); long body	SOT38-1					

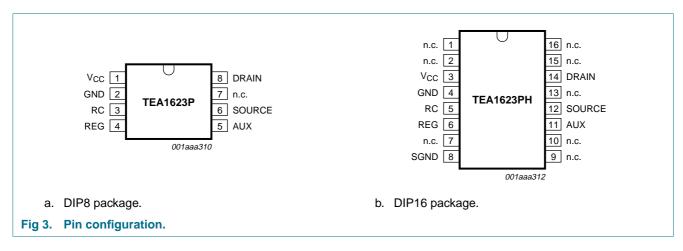
## 6. Block diagram





## 7. Pinning information

### 7.1 Pinning



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### 7.2 Pin description

Table 3: Pin description

Symbol	Pin		Description					
	TEA1623P TEA1623PH							
$V_{CC}$	1	3	supply voltage					
GND	2	4	ground					
RC	3	5	frequency setting					
REG	4	6	regulation input					
SGND	-	8	signal ground; must preferably be connected to pin GND					
AUX	5	11	input for voltage from auxiliary winding for timing (demagnetization)					
SOURCE	6	12	source of internal MOS switch					
n.c.	7	1, 2, 7, 9, 10, 13, 15, 16	not connected					
DRAIN	8	14	drain of internal MOS switch; input for start-up current and valley sensing					

### 8. Functional description

The TEA1623P; TEA1623PH is the heart of a compact flyback converter, with the IC placed at the primary side. The auxiliary winding of the transformer can be used for indirect feedback to control the isolated output. This additional winding also powers the IC. A more accurate control of the output voltage and/or current can be implemented with an additional secondary sensing circuit and optocoupler feedback.

The TEA1623P; TEA1623PH uses voltage mode control. The frequency is determined by the maximum transformer demagnetizing time and the time of the oscillator. In the first case, the converter operates in the Self Oscillating Power Supply (SOPS) mode. In the latter case, it operates at a constant frequency, which can be adjusted with external components  $R_{RC}$  and  $C_{RC}$ . This mode is called Pulse Width Modulation (PWM). Furthermore, a primary stroke is started only in a valley of the secondary ringing. This valley switching principle minimizes capacitive switch-on losses.

### 8.1 Start-up and undervoltage lock-out

Initially, the IC is self supplying from the rectified mains voltage. The IC starts switching as soon as the voltage on pin  $V_{CC}$  passes the  $V_{CC(start)}$  level. The supply is taken over by the auxiliary winding of the transformer as soon as  $V_{CC}$  is high enough and the supply from the line is stopped for high efficiency operation.

As soon as the voltage on pin  $V_{CC}$  drops below the  $V_{CC(stop)}$  level, the IC stops switching and restarts from the rectified mains voltage.

#### 8.2 Oscillator

The frequency of the oscillator is set by the external resistor and capacitor on pin RC. The external capacitor is charged rapidly to the  $V_{RC(max)}$  level and, starting from a new primary stroke, it discharges to the  $V_{RC(min)}$  level. Because the discharge is exponential, the relative sensitivity of the duty factor to the regulation voltage at low duty factor is almost

equal to the sensitivity at high duty factors. This results in a more constant gain over the duty factor range compared to PWM systems with a linear sawtooth oscillator. Stable operation at low duty factors is easily realized. For high efficiency, the frequency is reduced as soon as the duty factor drops below a certain value. This is accomplished by increasing the oscillator charge time.

To ensure that the capacitor can be charged within the charge time, the value of the oscillator capacitor should be limited to approximately 1 nF.

### 8.3 Duty factor control

The duty factor is controlled by the internal regulation voltage and the oscillator signal on pin RC. The internal regulation voltage is equal to the external regulation voltage (minus 2.5 V) multiplied by the gain of the error amplifier (typical 20 dB or  $10 \times$ ).

The minimum duty factor of the switched mode power supply is 0 %. The maximum duty factor is set to 75 % (typical value at 100 kHz oscillation frequency).

### 8.4 Valley switching

A new cycle is started at the primary stroke when the switch is switched on (see Figure 4). After a certain time (determined by the RC oscillator voltage and the internal regulation level), the switch is turned off and the secondary stroke starts. The internal regulation level is determined by the voltage on pin REG. After the secondary stroke, the drain voltage shows an oscillation with a frequency of approximately  $\frac{1}{2\pi \times \sqrt{L_n C_n}}$ 

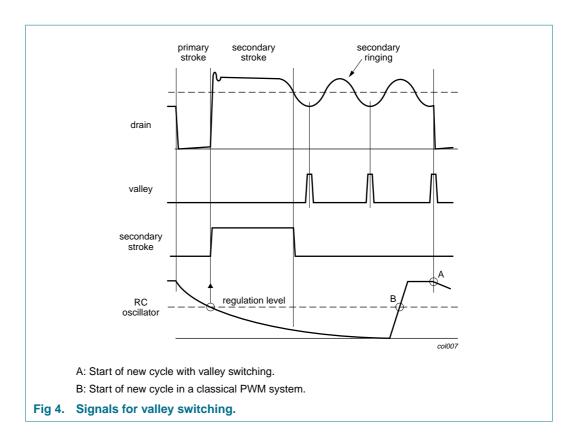
Where:

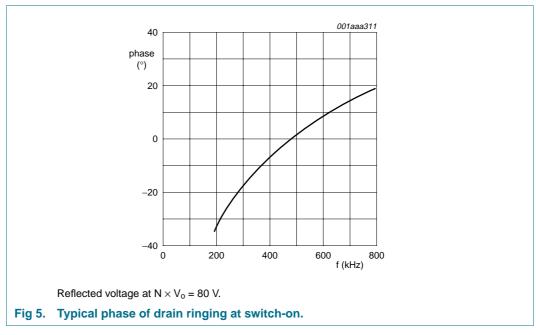
Lp is the primary self inductance on the drain node

C<sub>p</sub> is the parasitic capacitance on the drain node.

As soon as the oscillator voltage is high again and the secondary stroke has ended, the circuit waits for a low drain voltage before starting a new primary stroke.

The primary stroke starts some time before the actual valley at low ringing frequencies, and some time after the actual valley at high ringing frequencies. Figure 5 shows a typical curve for a reflected voltage N  $\times$  Vo of 80 V. This voltage is the output voltage Vo (see Figure 6) transferred to the primary side of the transformer with the factor N (determined by the turns ratio of the transformer). Figure 5 shows that the system switches exactly at minimum drain voltage for ringing frequencies of 480 kHz, thus reducing the switch-on losses to a minimum. At 200 kHz, the next primary stroke is started at 33° before the valley. The switch-on losses are still reduced significantly.





### 8.5 Demagnetization

The system operates in discontinuous conduction mode all the time. As long as the secondary stroke has not ended, the oscillator will not start a new primary stroke. During the suppression time  $t_{\text{suppr}}$ , demagnetization recognition is suppressed. This suppression may be necessary in applications where the transformer has a large leakage inductance and at low output voltages.

#### 8.6 Protections

### 8.6.1 Overcurrent protection

The cycle-by-cycle peak drain current limit circuit uses the external source resistor  $R_l$  (see Figure 6) to measure the current. The circuit is activated after the leading edge blanking time  $t_{leb}$ . The protection circuit limits the source voltage to  $V_{source(max)}$ , and thus limits the primary peak current.

### 8.6.2 Short winding protection

The short winding protection circuit is also activated after the leading edge blanking time. If the source voltage exceeds the short winding protection voltage  $V_{swp}$ , the TEA1623P; TEA1623PH stops switching. Only a power-on reset will restart normal operation. The short winding protection also protects in case of a secondary diode short circuit.

#### 8.6.3 Overtemperature protection

An accurate temperature protection is provided in the TEA1623P; TEA1623PH. When the junction temperature exceeds the thermal shutdown temperature, the IC stops switching. During thermal protection, the IC current is lowered to the start-up current. The IC continues normal operation as soon as the overtemperature situation has disappeared.

#### 8.6.4 Overvoltage protection

Overvoltage protection can be achieved in the application by pulling pin REG above its normal operation level, or by keeping the level of pin AUX above  $V_{demag}$ . The current primary stroke is terminated immediately, and no new primary stroke is started until the voltage on pin REG drops to its normal operation level. Pin REG has an internal clamp. The current feed into pin REG must be limited.

### 8.7 Characteristics of the complete power-plug

#### 8.7.1 Input

The input voltage range comprises the universal AC mains from 80 V to 276 V.

### 8.7.2 Accuracy

The accuracy of the complete converter, functioning as a voltage source with primary sensing, is approximately 8 % (mainly dependent on the transformer coupling). The accuracy with secondary sensing is defined by the accuracy of the external components. For safety requirements in case of optocoupler feedback loss, the primary sensing remains active when an overvoltage circuit is connected.

**Product data sheet** 

### 8.7.3 Efficiency

An efficiency of 75 % at maximum output power can be achieved for a complete converter designed for universal mains.

### **8.7.4** Ripple

A minimum ripple is obtained in a system designed for a maximum duty factor of 50 % under normal operating conditions, and a minimized dead time. The magnitude of the ripple in the output voltage is determined by the frequency and duty factor of the converter, the output current level, and the value and ESR of the output capacitor.

### 9. Limiting values

**Table 4: Limiting values**In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
Voltages						
V <sub>CC</sub>	supply voltage	continuous	[1]	-0.4	+40	V
V <sub>RC</sub>	oscillator input voltage		<u>[1]</u>	-0.4	+3	V
V <sub>SOURCE</sub>	DMOS power transistor source voltage			-0.4	+5	V
$V_{DRAIN}$	DMOS power transistor drain voltage			-0.4	+650	V
Currents						
I <sub>REG</sub>	regulation input current		[2]	-	6	mΑ
I <sub>AUX</sub>	auxiliary winding input current		[2]	-10	+5	mΑ
I <sub>RC</sub>	oscillator capacitor charge current			-3	-	mA
I <sub>SOURCE</sub>	source current			-2	+2	Α
I <sub>DRAIN</sub>	drain current			-2	+2	Α
General						
P <sub>tot</sub>	total power dissipation					
	TEA1623P	T <sub>amb</sub> < 45 °C		-	1.0	W
	TEA1623PH	T <sub>amb</sub> < 50 °C		-	1.7	W
T <sub>stg</sub>	storage temperature			-55	+150	°C
T <sub>amb</sub>	ambient temperature			-20	+85	°C
Tj	junction temperature			-20	+145	°C
V <sub>esd</sub>	electrostatic discharge voltage	human body model	[3]			
		pin DRAIN		-1500	+1500	V
		all other pins		-2000	+2000	V
		machine model	<u>[4]</u>			
		all pins		-200	+200	V

<sup>[1]</sup> Pins  $V_{CC}$  and RC are not allowed to be current driven.

<sup>[2]</sup> Pins REG and AUX are not allowed to be voltage driven.

<sup>[3]</sup> Human body model: equivalent to discharging a 100 pF capacitor through a 1.5 k $\Omega$  series resistor.

[4] Machine model: equivalent to discharging a 200 pF capacitor through a 0.75 μH coil and a 10 Ω series resistor.

### 10. Thermal characteristics

Table 5: Thermal characteristics

Symbol	Parameter	Conditions	Тур	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	<u>[1]</u>	
	TEA1623P		100	K/W
	TEA1623PH		55	K/W

<sup>[1]</sup> Thermal resistance  $R_{th(j-a)}$  can be lower when pin GND is connected to sufficient copper area on the printed-circuit board. See the TEA152x application notes for details.

### 11. Characteristics

**Table 6: Characteristics** 

 $T_{amb}$  = 25 °C; no overtemperature; all voltages are measured with respect to ground; currents are positive when flowing into the IC; unless otherwise specified.

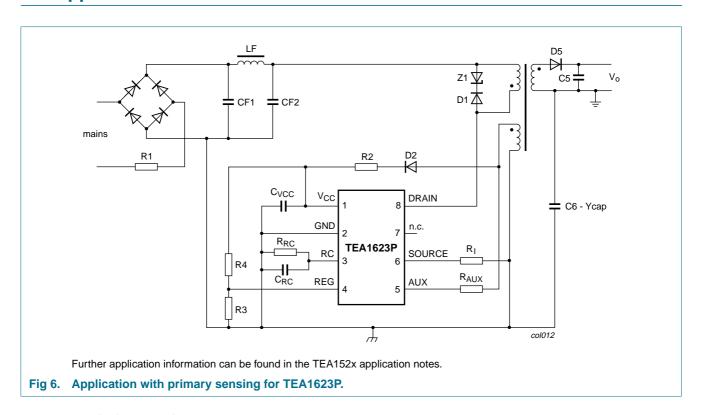
Symbol	Parameter	Conditions	Min	Тур	Max	Uni
Supplies						
Supply on p	oin V <sub>CC</sub>					
V <sub>CC(start)</sub>	start voltage		9	9.5	10	V
V <sub>CC(stop)</sub>	stop voltage	undervoltage lock-out	7.0	7.5	8.0	V
I <sub>CC(operate)</sub>	operating supply current	normal operation	-	1.3	1.9	mΑ
I <sub>CC(startup)</sub>	start-up supply current	start-up	-	180	400	μΑ
I <sub>CC(ch)</sub>	charging current	V <sub>DRAIN</sub> > 60 V				
		$V_{CC} = 0 V$	-650	-520	-390	μΑ
		V <sub>CC</sub> = 8.5 V	-375	-275	-175	μΑ
Supply on p	oin DRAIN					
I <sub>DRAIN</sub>	supply current drawn from pin DRAIN	no auxiliary supply	-	0.5	-	mΑ
		with auxiliary supply; V <sub>DRAIN</sub> > 60 V	-	30	125	μΑ
Pulse widtl	h modulator mode					
$\delta_{min}$	minimum duty factor		-	0	-	%
$\delta_{\text{max}}$	maximum duty factor	f <sub>osc</sub> = 100 kHz	-	75	-	%
Self oscilla	ting power supply mode					
V <sub>demag</sub>	demagnetization recognition voltage level		50	100	150	mV
t <sub>suppr</sub>	time of suppression of transformer ringing at start of secondary stroke		1.0	1.5	2.0	μs
Oscillator:	pin RC					
$V_{RC(min)}$	minimum voltage of RC oscillator setting		60	75	90	mV
$V_{RC(max)}$	maximum voltage of RC oscillator setting		2.4	2.5	2.6	V
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					-	

 Table 6:
 Characteristics ...continued

 $T_{amb}$  = 25 °C; no overtemperature; all voltages are measured with respect to ground; currents are positive when flowing into the IC; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Uni
t <sub>RC(ch)</sub>	RC charging time		-	1	-	μs
f <sub>osc</sub>	oscillator frequency range		10	-	200	kHz
<b>Duty factor</b>	regulator: pin REG					
$V_{REG}$	input voltage on pin REG		2.4	2.5	2.6	V
G <sub>V(erroramp)</sub>	voltage gain of error amplifier		-	20	-	dB
V <sub>REG(clamp)</sub>	clamping voltage on pin REG	I <sub>REG</sub> = 6 mA	-	-	7.5	V
Valley switc	hing recognition					
dV/dt <sub>valley</sub>	valley recognition		-102	-	+102	V/µs
f <sub>valley</sub>	ringing frequency for valley switching	$N \times V_0 = 100 \text{ V}$	200	550	800	kHz
t <sub>d(valley-on)</sub>	delay from valley recognition to switch-on		-	150	-	ns
Output stag	e (FET)					
I <sub>L(drain)</sub>	drain leakage current	$V_{DRAIN} = 650 \text{ V}$	-	-	125	μΑ
V <sub>BR(drain)</sub>	drain breakdown voltage	T <sub>j</sub> > 0 °C	650	-	-	V
R <sub>DSon</sub>	drain-source on-state resistance	$I_{SOURCE} = -0.5 A$				
		T <sub>j</sub> = 25 °C	-	6.5	7.5	Ω
		T <sub>j</sub> = 100 °C	-	9.0	10.0	Ω
t <sub>drain(f)</sub>	drain fall time	V <sub>DRAIN(switch_on)</sub> = 300 V; no external capacitor at pin DRAIN	-	75	-	ns
Temperature	e protection					
T <sub>prot(max)</sub>	maximum threshold temperature		150	160	170	°C
T <sub>prot(hys)</sub>	threshold temperature hysteresis		-	2	-	°C
Overcurrent	and short winding protection: pin SO	URCE				
V <sub>source(max)</sub>	overcurrent protection voltage	$dV/dt = 0.1 V/\mu s$	0.47	0.50	0.53	V
V <sub>swp</sub>	short winding protection voltage	$dV/dt = 0.5 V/\mu s$	0.7	0.75	0.8	V
t <sub>d(propagation)</sub>	delay from detecting $V_{\text{source}(\text{max})}$ to switch-off	$dV/dt = 0.5 V/\mu s$	-	160	185	ns
t <sub>leb</sub>	leading edge blanking time	both overcurrent and short winding protection	250	350	450	ns

## 12. Application information



### 13. Test information

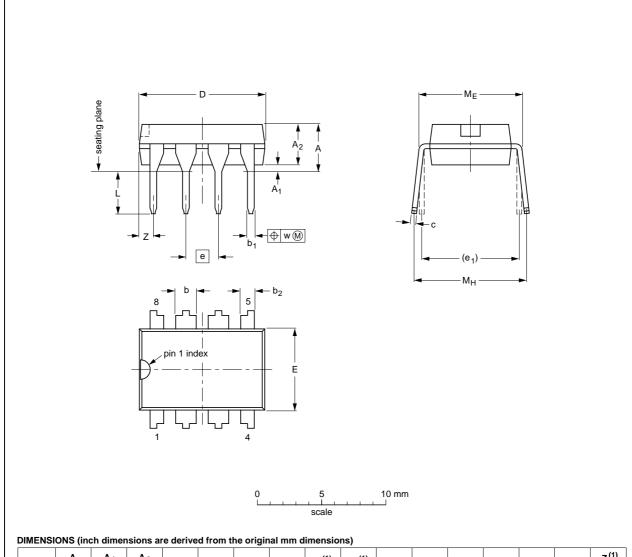
### 13.1 Quality information

The General Quality Specification for Integrated Circuits, SNW-FQ-611 is applicable.

## 14. Package outline

### DIP8: plastic dual in-line package; 8 leads (300 mil)

SOT97-1



UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	b <sub>2</sub>	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	e <sub>1</sub>	L	ME	Мн	w	Z <sup>(1)</sup> max.
mm	4.2	0.51	3.2	1.73 1.14	0.53 0.38	1.07 0.89	0.36 0.23	9.8 9.2	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	1.15
inche	0.17	0.02	0.13	0.068 0.045	0.021 0.015	0.042 0.035	0.014 0.009	0.39 0.36	0.26 0.24	0.1	0.3	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.045

#### Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

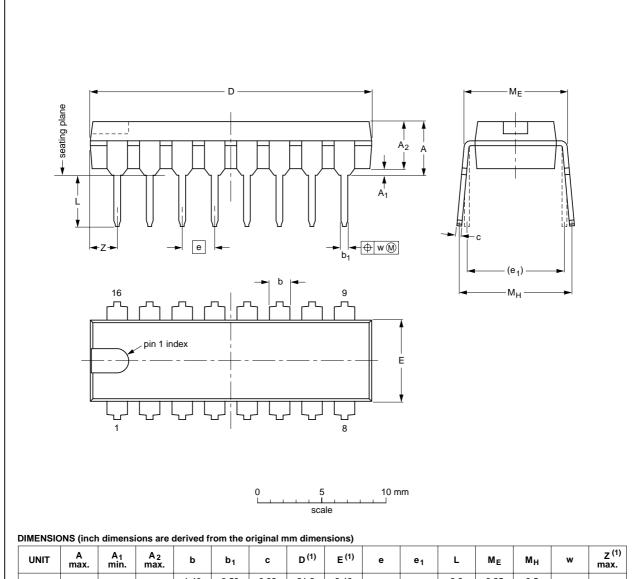
OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT97-1	050G01	MO-001	SC-504-8			<del>99-12-27</del> 03-02-13

Fig 7. Package outline DIP8.

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DIP16: plastic dual in-line package; 16 leads (300 mil); long body

SOT38-1



UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	e <sub>1</sub>	L	ME	Мн	w	Z <sup>(1)</sup> max.
mm	4.7	0.51	3.7	1.40 1.14	0.53 0.38	0.32 0.23	21.8 21.4	6.48 6.20	2.54	7.62	3.9 3.4	8.25 7.80	9.5 8.3	0.254	2.2
inches	0.19	0.02	0.15	0.055 0.045	0.021 0.015	0.013 0.009	0.86 0.84	0.26 0.24	0.1	0.3	0.15 0.13	0.32 0.31	0.37 0.33	0.01	0.087

#### Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE	
VERSION	IEC	IEC JEDEC		PROJECTION	ISSUE DATE
SOT38-1	050G09	MO-001	SC-503-16		<del>99-12-27</del> 03-02-13

Fig 8. Package outline DIP16.

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### 15. Soldering

### 15.1 Introduction to soldering through-hole mount packages

This text gives a brief insight to wave, dip and manual soldering. A more in-depth account of soldering ICs can be found in our *Data Handbook IC26; Integrated Circuit Packages* (document order number 9398 652 90011).

Wave soldering is the preferred method for mounting of through-hole mount IC packages on a printed-circuit board.

### 15.2 Soldering by dipping or by solder wave

Driven by legislation and environmental forces the worldwide use of lead-free solder pastes is increasing. Typical dwell time of the leads in the wave ranges from 3 to 4 seconds at 250 °C or 265 °C, depending on solder material applied, SnPb or Pb-free respectively.

The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature  $(T_{stg(max)})$ . If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

### 15.3 Manual soldering

Apply the soldering iron (24 V or less) to the lead(s) of the package, either below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300  $^{\circ}$ C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400  $^{\circ}$ C, contact may be up to 5 seconds.

### 15.4 Package related soldering information

Table 7: Suitability of through-hole mount IC packages for dipping and wave soldering methods

Package	Soldering method				
	Dipping	Wave			
DBS, DIP, HDIP, RDBS, SDIP, SIL	suitable	suitable [1]			
PMFP [2]	_	not suitable			

<sup>[1]</sup> For SDIP packages, the longitudinal axis must be parallel to the transport direction of the printed-circuit board.

<sup>[2]</sup> For PMFP packages hot bar soldering or manual soldering is suitable.

# **TEA1623P; TEA1623PH**



## 16. Revision history

### Table 8: Revision history

Document ID	Release date	Data sheet status	Change notice	Order number	Supersedes
TEA1623P_TEA1623PH_1	20040317	Product data	-	9397 750 12579	-



Level	Data sheet status [1]	Product status [2] [3]	Definition
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
III	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

- [1] Please consult the most recently issued data sheet before initiating or completing a design.
- [2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.
- [3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

### 18. Definitions

**Short-form specification** — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

**Application information** — Applications that are described herein for any of these products are for illustrative purposes only. Philips Semiconductors make no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

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#### 21. Contact information

For additional information, please visit: http://www.semiconductors.philips.com
For sales office addresses, send an email to: sales.addresses@www.semiconductors.philips.com



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